

BAS21AHT1G

Preferred Device

Low Leakage Switching Diode

Features

- This is a Pb-Free Device

MAXIMUM RATINGS

| Symbol | Rating | Value | Unit |
|-----------------|---------------------------------|-------|------|
| V_R | Continuous Reverse Voltage | 250 | Vdc |
| V_{RRM} | Repetitive Peak Reverse Voltage | 250 | Vdc |
| I_F | Peak Forward Current | 200 | mAdc |
| $I_{FM(surge)}$ | Peak Forward Surge Current | 625 | mAdc |

THERMAL CHARACTERISTICS

| Symbol | Characteristic | Max | Unit |
|-----------------|---|-------------|---------------------------|
| P_D | Total Device Dissipation FR-5 Board, (Note 1) $T_A = 25^\circ\text{C}$ | 200 | mW |
| | Derate above 25°C | 1.57 | mW/ $^\circ\text{C}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | 635 | $^\circ\text{C}/\text{W}$ |
| T_J, T_{stg} | Junction and Storage Temperature Range | -55 to +150 | $^\circ\text{C}$ |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

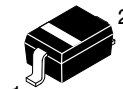
1. FR-5 Minimum Pad



ON Semiconductor®

<http://onsemi.com>

LOW LEAKAGE SWITCHING DIODE



SOD-323
CASE 477
STYLE 1

MARKING DIAGRAM



AA = Device Code
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

| Device | Package | Shipping† |
|------------|----------------------|------------------|
| BAS21AHT1G | SOD-323 (Pb-Free) | 3000/Tape & Reel |

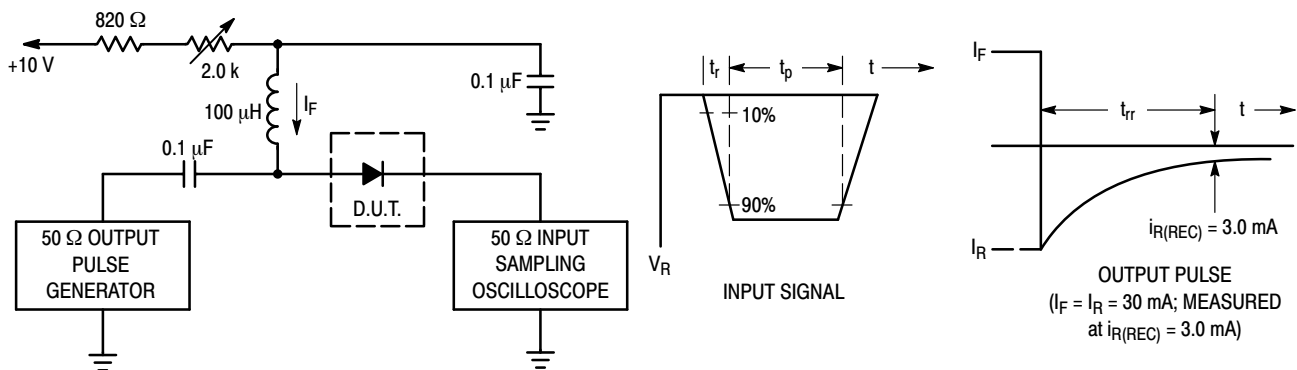
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

BAS21AHT1G

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|---|------------|--------|--------|--------------|-------------------------|
| OFF CHARACTERISTICS | | | | | |
| Reverse Voltage Leakage Current ($V_R = 200\text{ Vdc}$) ($V_R = 200\text{ Vdc}$, $T_J = 150^\circ\text{C}$) | I_R | - | - | 40 100 | nAdc μAdc |
| Reverse Breakdown Voltage ($I_{BR} = 100\ \mu\text{Adc}$) | $V_{(BR)}$ | 250 | - | - | Vdc |
| Forward Voltage ($I_F = 100\ \text{mAdc}$) ($I_F = 200\ \text{mAdc}$) | V_F | - - | - - | 1000 1250 | mV |
| Diode Capacitance ($V_R = 0$, $f = 1.0\ \text{MHz}$) | C_D | - | - | 5.0 | pF |
| Reverse Recovery Time ($I_F = I_R = 30\ \text{mAdc}$, $R_L = 100\ \Omega$) | t_{rr} | - | 50 | - | ns |



- Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 30 mA.
 2. Input pulse is adjusted so $I_{R(\text{peak})}$ is equal to 30 mA.
 3. $t_p \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

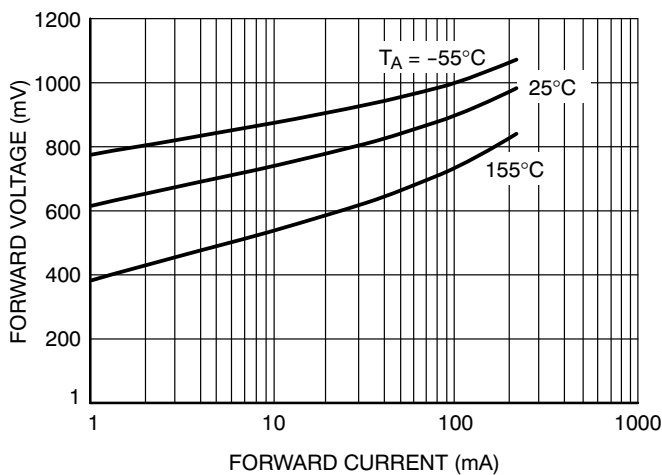


Figure 2. Forward Voltage

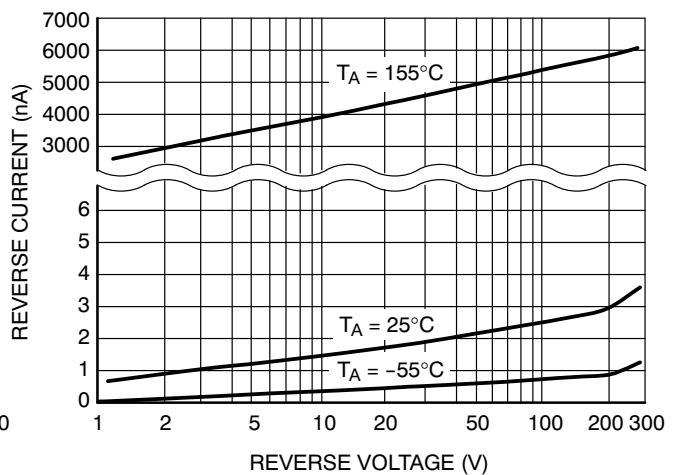
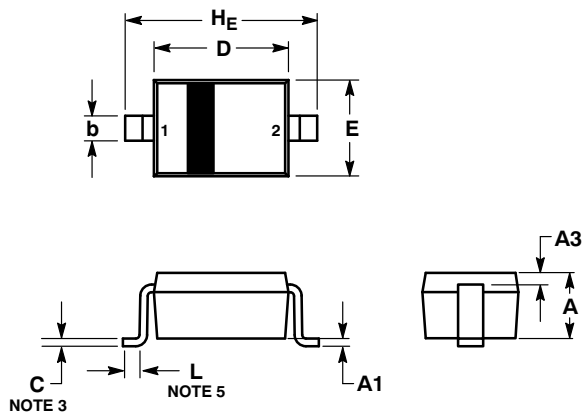


Figure 3. Reverse Leakage

BAS21AHT1G

PACKAGE DIMENSIONS

SOD-323
PLASTIC PACKAGE
CASE 477-02
ISSUE H



NOTES:

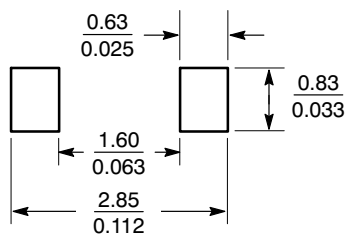
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
5. DIMENSION L IS MEASURED FROM END OF RADIUS.

| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|-------|-----------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.80 | 0.90 | 1.00 | 0.031 | 0.035 | 0.040 |
| A1 | 0.00 | 0.05 | 0.10 | 0.000 | 0.002 | 0.004 |
| A3 | 0.15 REF | | | 0.006 REF | | |
| b | 0.25 | 0.32 | 0.4 | 0.010 | 0.012 | 0.016 |
| C | 0.089 | 0.12 | 0.177 | 0.003 | 0.005 | 0.007 |
| D | 1.60 | 1.70 | 1.80 | 0.062 | 0.066 | 0.070 |
| E | 1.15 | 1.25 | 1.35 | 0.045 | 0.049 | 0.053 |
| L | 0.08 | | | 0.003 | | |
| HE | 2.30 | 2.50 | 2.70 | 0.090 | 0.098 | 0.105 |

STYLE 1:

1. CATHODE
2. ANODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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